N-Channel 150-V (D-S) 175 °C MOSFET

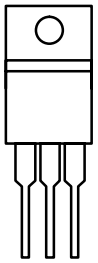
PRODUCT SUMMARY		
V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
150	0.095 at V_{GS} = 10 V	18
	0.100 at V_{GS} = 6 V	17.5

FEATURES

- TrenchFET® Power MOSFET
- 175 °C Junction Temperature

Available
RoHS* COMPLIANT

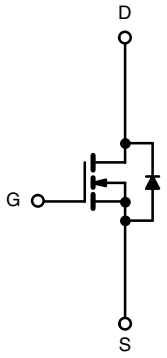
TO-220AB



G D S

Top View

DRAIN connected to TAB



N-Channel MOSFET

Ordering Information: SUP18N15-95
SUP18N15-95-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted				
Parameter		**Symbol**	**Limit**	**Unit**
Drain-Source Voltage		V_{DS}	150	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 175 °C)	T_C = 25 °C	I_D	18	A
	T_C = 125 °C		10.3	
Pulsed Drain Current		I_{DM}	25	
Avalanche Current		I_{AS}	15	
Single Pulse Avalanche Energy[a]	L = 0.1 mH	E_{AS}	16.2	mJ
Maximum Power Dissipation[a]	T_C = 25 °C	P_D	88[b]	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS			
Parameter	**Symbol**	**Limit**	**Unit**
Junction-to-Ambient (Free Air)	R_{thJA}	85	°C/W
Junction-to-Case	R_{thJC}	1.7	

Notes:
a. Duty cycle ≤ 1 %.
b. See SOA curve for voltage derating.

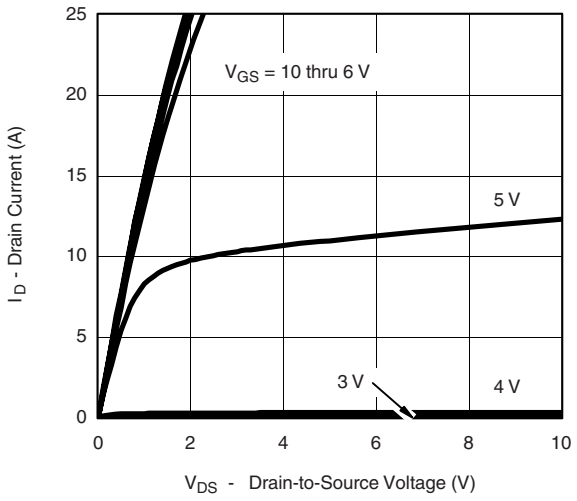
* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Min**	**Typ[a]**	**Max**	**Unit**
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 µA	150			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	2			
Gate-Body Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 120 V, V_{GS} = 0 V			1	µA
		V_{DS} = 120 V, V_{GS} = 0 V, T_J = 125 °C			50	
		V_{DS} = 120 V, V_{GS} = 0 V, T_J = 175 °C			250	
On-State Drain Current[b]	$I_{D(on)}$	V_{DS} = 5 V, V_{GS} = 10 V	25			A
Drain-Source On-State Resistance[b]	$r_{DS(on)}$	V_{GS} = 10 V, I_D = 15 A		0.077	0.095	Ω
		V_{GS} = 10 V, I_D = 15 A, T_J = 125 °C			0.190	
		V_{GS} = 10 V, I_D = 15 A, T_J = 175 °C			0.250	
		V_{GS} = 6 V, I_D = 10 A		0.081	0.100	
Forward Transconductance[b]	g_{fs}	V_{DS} = 15 V, I_D = 15 A		25		S
Dynamic[a]						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1 MHz		900		pF
Output Capacitance	C_{oss}			115		
Reverse Transfer Capacitance	C_{rss}			70		
Total Gate Charge[c]	Q_g	V_{DS} = 75 V, V_{GS} = 10 V, I_D = 15 A		20	25	nC
Gate-Source Charge[c]	Q_{gs}			5.5		
Gate-Drain Charge[c]	Q_{gd}			7		
Turn-On Delay Time[c]	$t_{d(on)}$	V_{DD} = 75 V, R_L = 5 Ω I_D ≅ 15 A, V_{GEN} = 10 V, R_G = 2.5 Ω		8	12	ns
Rise Time[c]	t_r			35	55	
Turn-Off Delay Time[c]	$t_{d(off)}$			17	25	
Fall Time[c]	t_f			30	45	
Source-Drain Diode Ratings and Characteristics (T_C = 25 °C)[b]						
Continuous Current	I_S				15	A
Pulsed Current	I_{SM}				25	
Forward Voltage[a]	V_{SD}	I_F = 15 A, V_{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	t_{rr}	I_F = 15 A, di/dt = 100 A/µs		55	85	ns
Peak Reverse Recovery Current	$I_{RM(REC)}$			5	8	A
Reverse Recovery Charge	Q_{rr}			0.13	0.34	µC

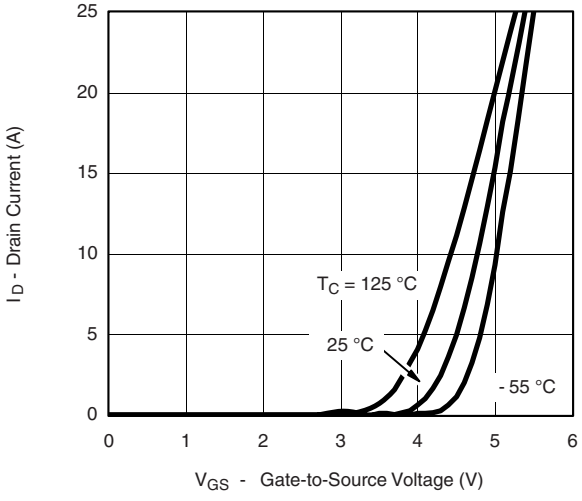
Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

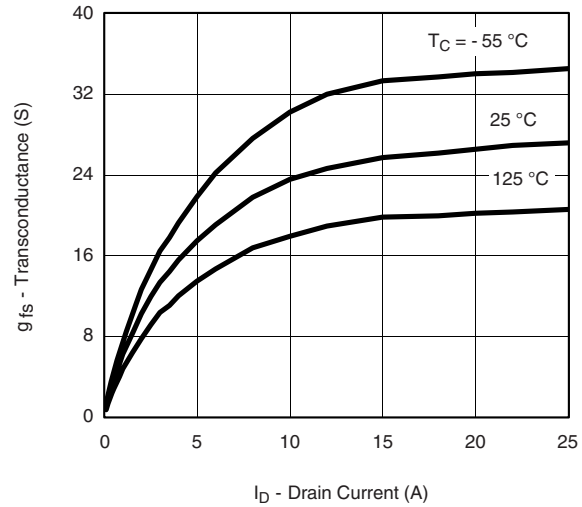
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



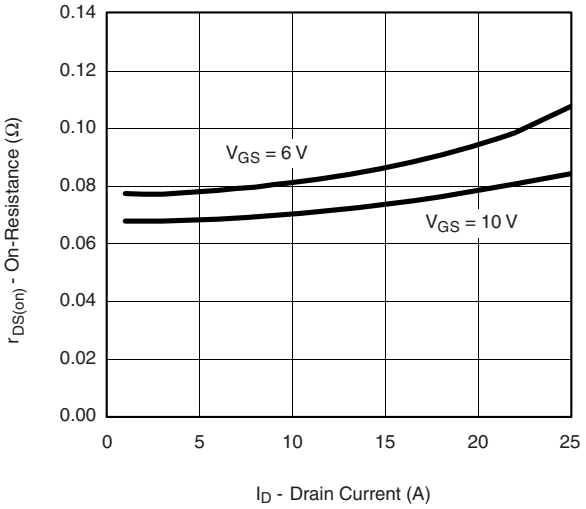
Output Characteristics



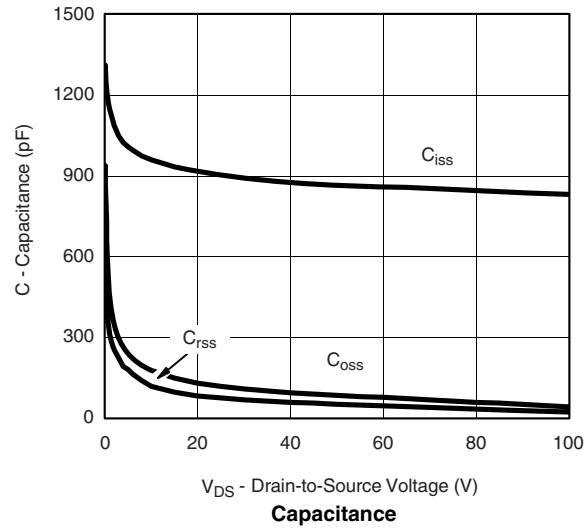
Transfer Characteristics



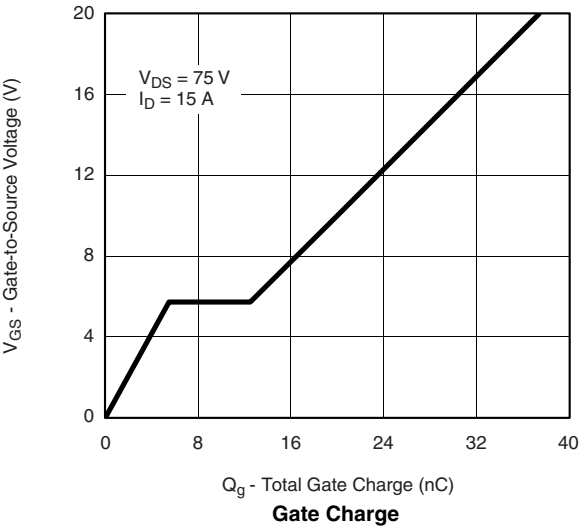
Transconductance



On-Resistance vs. Drain Current

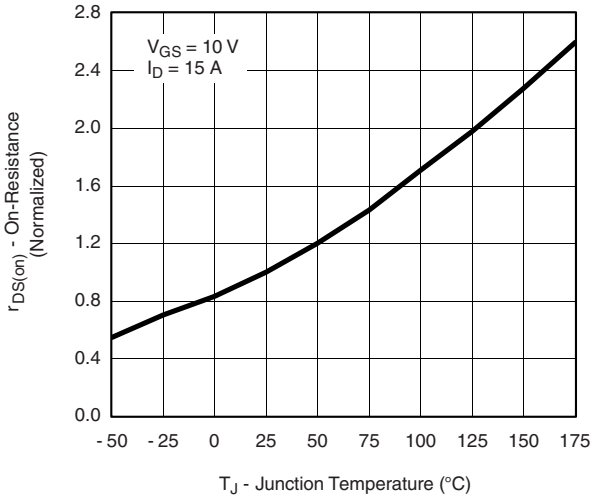


Capacitance

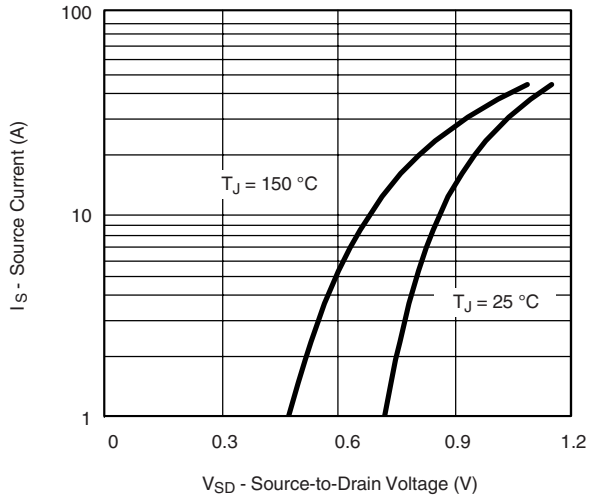


Gate Charge

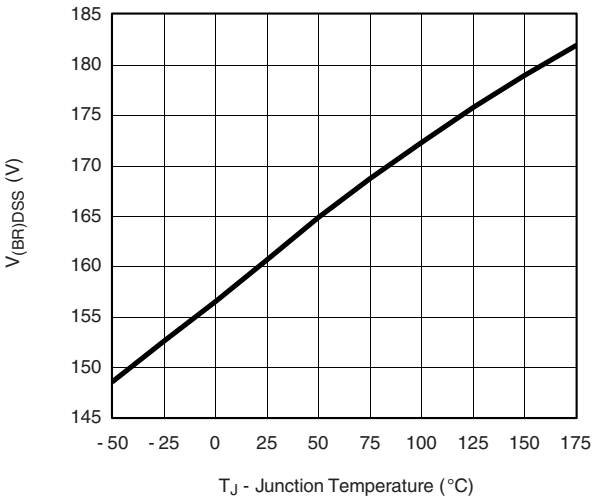
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



On-Resistance vs. Junction Temperature

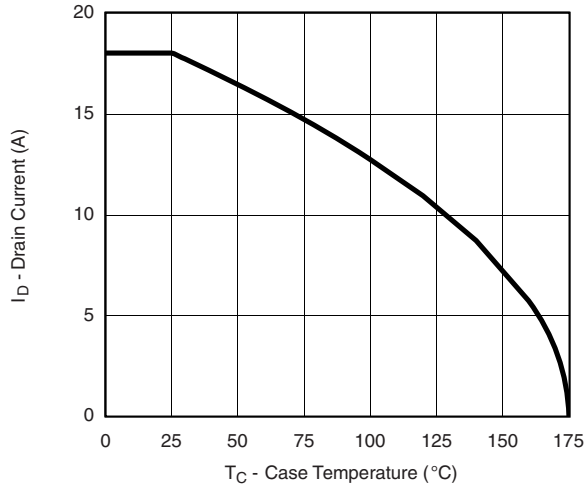


Source-Drain Diode Forward Voltage

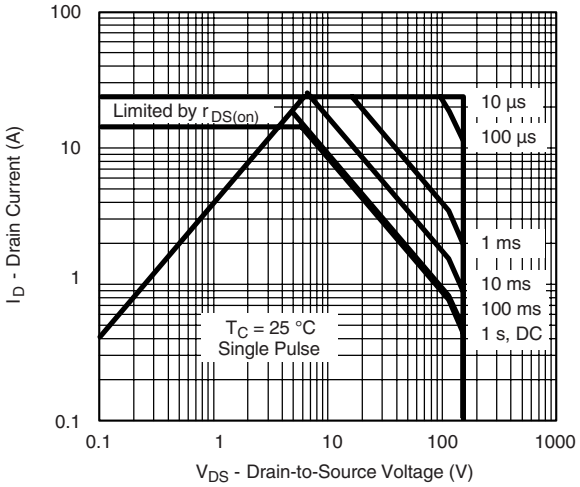


Drain-Source Voltage Breakdown vs. Junction Temperature

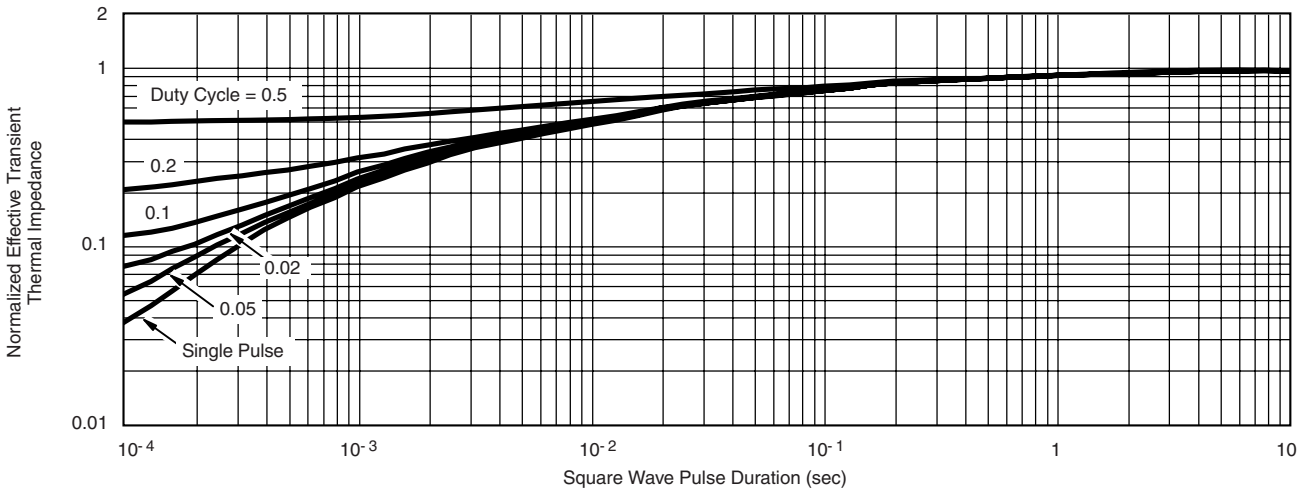
THERMAL RATINGS



Maximum Avalanche Drain Current vs. Case Temperature



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

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